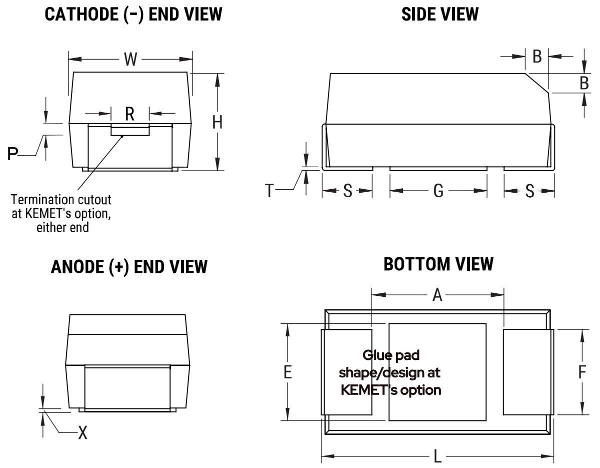
T493D337M006AT6120

T493 HRA, Tantalum, MnO2 Tantalum, HRA, 330 uF, 20%, 6.3 VDC, SMD, MnO2, Molded, High Reliability, N/A, 150 mOhms, 7343, 3.1 mm, 1.3 mm



Click here for the 3D model.

General Information	
Series	T493 HRA
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, High Reliability
Features	High Reliability
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	412.33 mg
Notes	P and R dimensions represents the minimum solderable area of the termination surface entirely below cutout (if one is present).

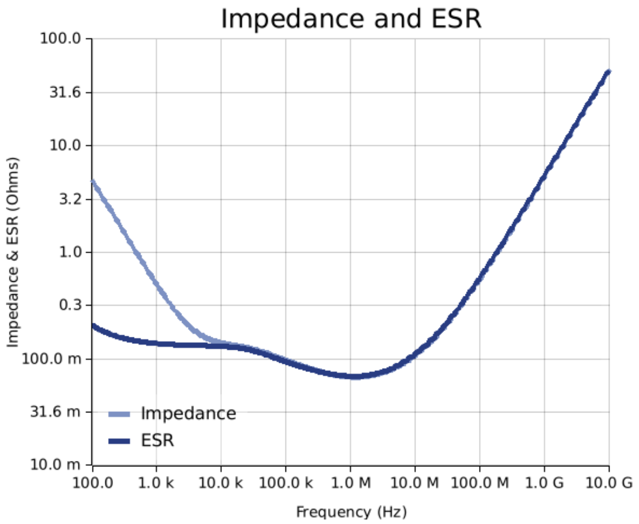
Dimensions	
L	7.3mm +/-0.3mm
W	4.3mm +/-0.3mm
H	2.8mm +/-0.3mm
T	0.13mm REF
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
A	3.8mm MIN
B	0.5mm +/-0.15mm
E	3.5mm REF
G	3.5mm REF
P	0.5mm MIN
R	1mm REF
X	0.1mm +/-0.1mm REF

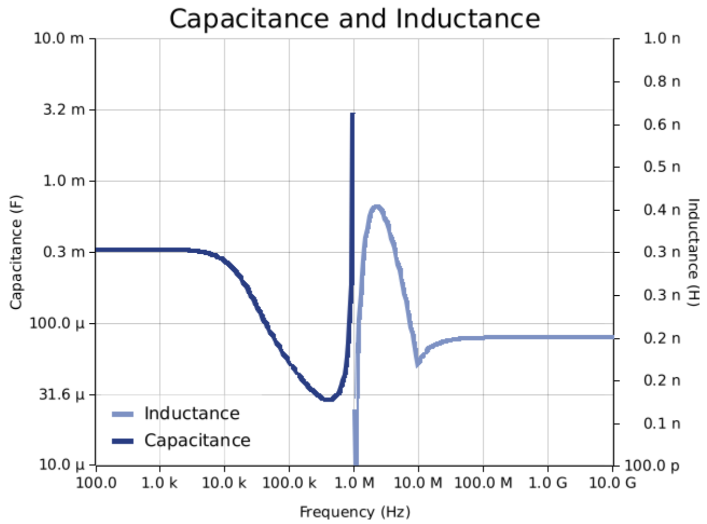
Specifications	
Capacitance	330 uF
Tolerance	20%
Voltage DC	6.3 VDC (85C), 4.22 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	8% 120Hz 25C
Failure Rate	N/A
ESR	0.15 Ohms (100kHz 25C)
Ripple Current	1000 mA (rms, 100kHz 25C)
Leakage Current	20.8 uA (5min 25°C)
Testing and Reliability	Standard Testing Only

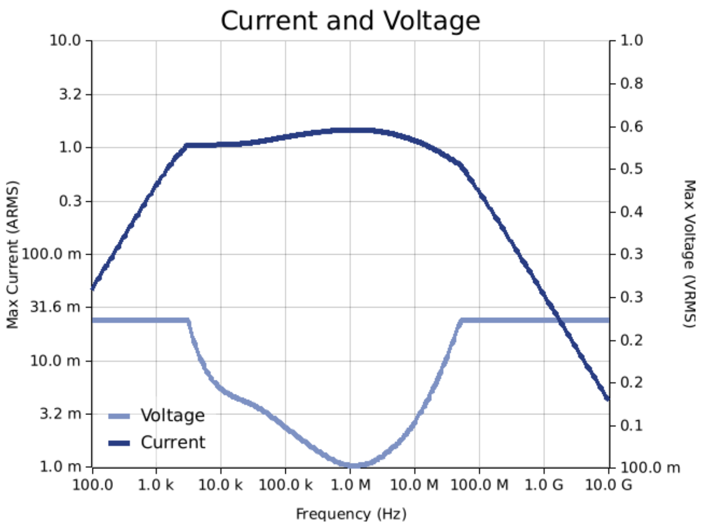
Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	500

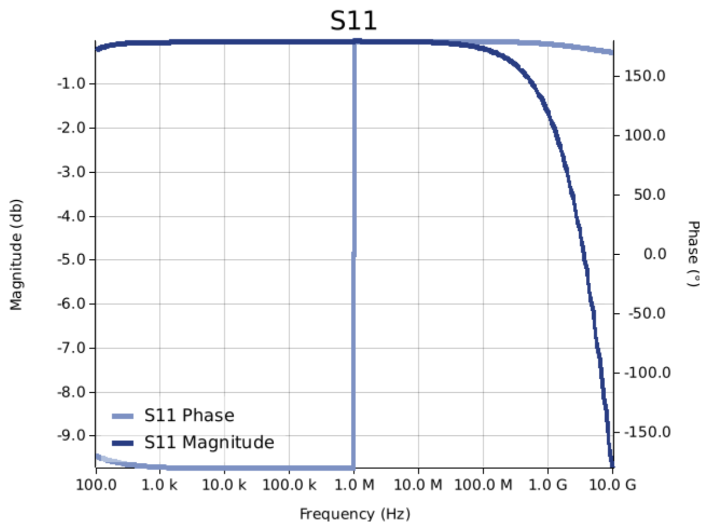
Simulations

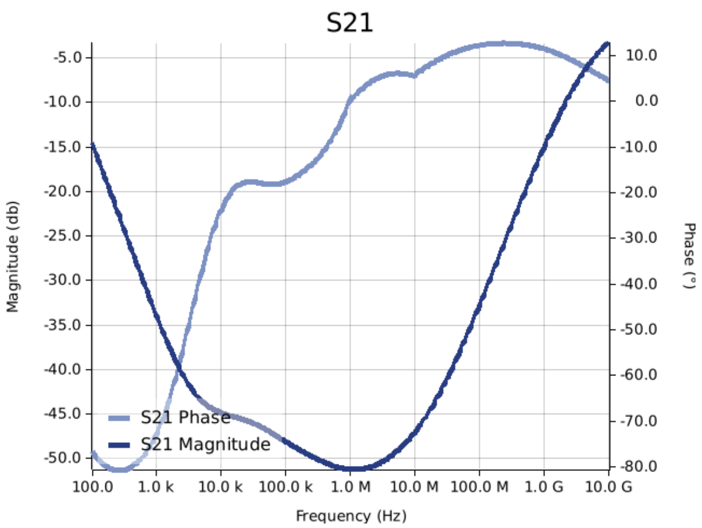
For the complete simulation environment please visit K-SIM.











These are simulations.
This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple “Ripple Current/Voltage vs. Frequency” plots is the ESR at ambient temperature.
- The ESR in the “Temperature Rise vs. Ripple Current” plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
- The peak voltages generated in the “Temperature Rise vs. Combined Ripple Currents” plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

If you have any questions please contact K-SIM.